

Claims

1. (Canceled)
2. (Currently amended) ~~A~~ The TAB tape according to claim 1 wherein comprising:
a tape substrate of insulating material;
a first wiring pattern of conductive material, said first wiring pattern being formed on one
surface of said tape substrate;
a second wiring pattern of conductive material, said second wiring pattern being formed
on the other surface of said tape substrate;
a conduction part that allows electrical conduction between said first wiring pattern and
said second wiring pattern; and
a stiffener that is adhered through adhesive to the other surface of said tape substrate;
wherein said second wiring pattern includes an insulating material filled in a groove
region where no wiring pattern is formed around wiring patterns of said second wiring pattern,
said insulating material is photosensitive solder resist.
3. The TAB tape according to claim 2, wherein:
said photosensitive solder resist has a thickness of -10 to +20 μm comparing to that of
wiring patterns of said second wiring pattern.
4. The TAB tape according to claim 2, wherein:
said photosensitive solder resist is filled in said groove region by screen printing.

5. (Canceled)

6. (Currently amended) A The method of making a TAB tape according to claim 5 wherein comprising the steps of:
forming a first wiring pattern of conductive material on one surface of a tape substrate of insulating material,
forming a second wiring pattern of conductive material on the other surface of said tape substrate;
forming a conduction part that allows electrical conduction between said first wiring pattern and said second wiring pattern;
and
adhering a stiffener through adhesive to the other surface of said tape substrate;
wherein said adhering step is conducted after filling an insulating material in a groove region where no wiring pattern is formed around wiring patterns of said second wiring pattern,
said insulating material is photosensitive solder resist.

7. (Previously presented) The method of making a TAB tape according to claim 6, wherein:
said photosensitive solder resist has a thickness of -10 to +20 μm comparing to that of wiring patterns of said second wiring pattern.

8. (Previously presented) The method of making a TAB tape according to claim 6, wherein:

said photosensitive solder resist is filled in said groove region by screen printing.

9. (Canceled)

10. (Currently amended) A The semiconductor device according to claim 9 wherein comprising:

a tape substrate of insulating material, said tape substrate including an opening;

a first wiring pattern of conductive material, said first wiring pattern being formed on one surface of said tape substrate;

a second wiring pattern of conductive material, said second wiring pattern being formed on the other surface of said tape substrate;

a conduction part that allows electrical conduction between said first wiring pattern and said second wiring pattern; and

a stiffener that is adhered through adhesive to the other surface of said tape substrate;

a semiconductor chip that is mounted on said stiffener in the opening of said tape substrate;

bonding wires that connect between said semiconductor chip and said second wiring pattern; and

sealing resin that seals said semiconductor chip;

wherein said second wiring pattern includes an insulating material filled in a groove region where no wiring pattern is formed around wiring patterns of said second wiring pattern,
said insulating material is photosensitive solder resist.

11. (Previously presented) The semiconductor device according to claim 10, wherein:

said photosensitive solder resist has a thickness of -10 to +20 μm comparing to that of wiring patterns of said second wiring pattern.

12. (Previously presented) The semiconductor device according to claim 10, wherein:
said photosensitive solder resist is filled in said groove region by screen printing.